US00D956707S

(12) **United States Design Patent**
Yamauchi

(10) **Patent No.: US D956,707 S**
(45) **Date of Patent: ** Jul. 5, 2022**

(54) **CIRCUIT BOARD**

(71) Applicant: **LAPIS Semiconductor Co., Ltd.**, Yokohama (JP)

(72) Inventor: **Shigeki Yamauchi**, Yokohama (JP)

(73) Assignee: **LAPIS SEMICONDUCTOR CO., LTD.**, Yokohama (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/729,267**

(22) Filed: **Mar. 25, 2020**

(30) **Foreign Application Priority Data**

Sep. 26, 2019 (JP) 2019-21604
Sep. 26, 2019 (JP) 2019-21605
Sep. 26, 2019 (JP) 2019-21606

(51) **LOC (13) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/182; 361/748, 752, 760, 761, 807, 361/808, 736, 719, 720; 174/250, 253, 174/255, 68.1; 363/144, 147
CPC H05K 3/30; H05K 3/301; H05K 3/284; H05K 3/303; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/183; H05K 1/185; H05K 1/00; H05K 7/1417; H05K 7/02; H05K 7/12; H05K 7/06; H01L 2924/14
See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki
(74) *Attorney, Agent, or Firm* — Brooks Kushman P.C.

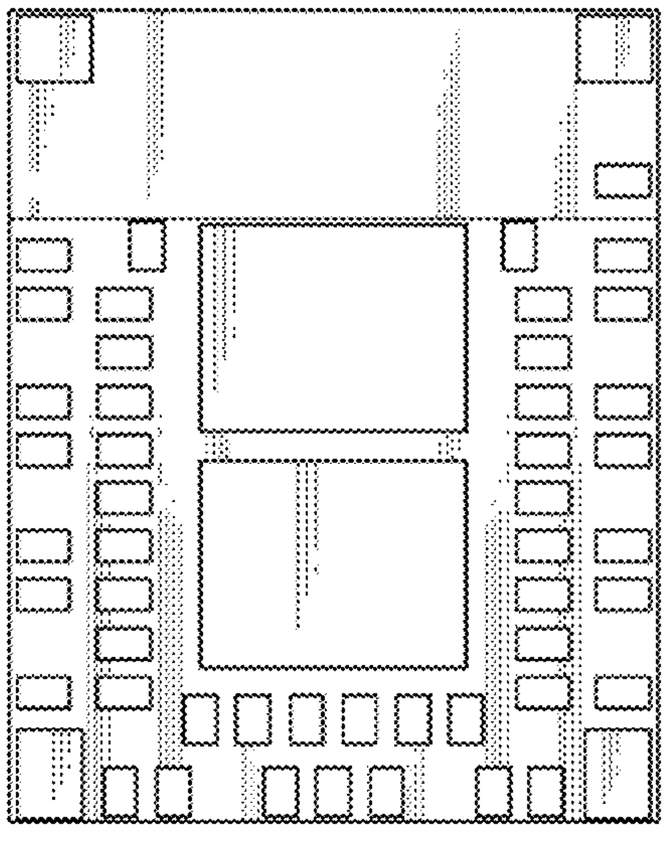
(57) **CLAIM**

The ornamental design for a circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a circuit board showing my new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a right side view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a top view thereof; and,
FIG. **6** is a bottom view thereof.
Throughout the drawings, the dash-dash broken lines are for the purpose of illustrating environment only and form no part of the claimed design.

1 Claim, 2 Drawing Sheets



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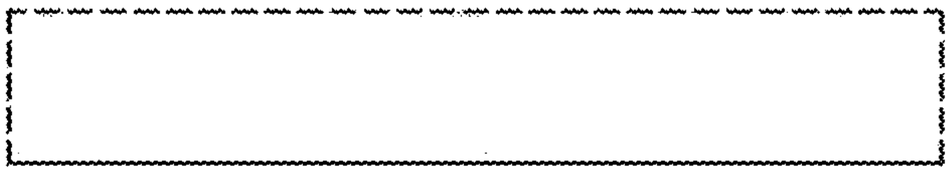

Fig-1

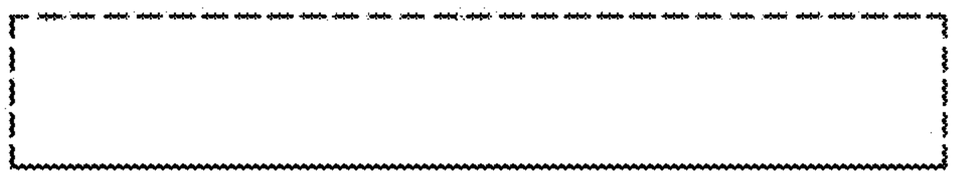

Fig-2

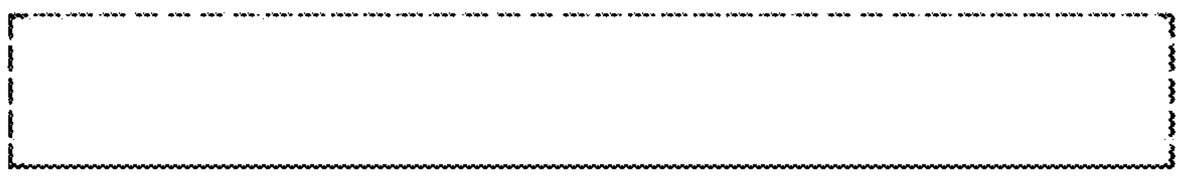

Fig-3

Fig-4

Fig-5

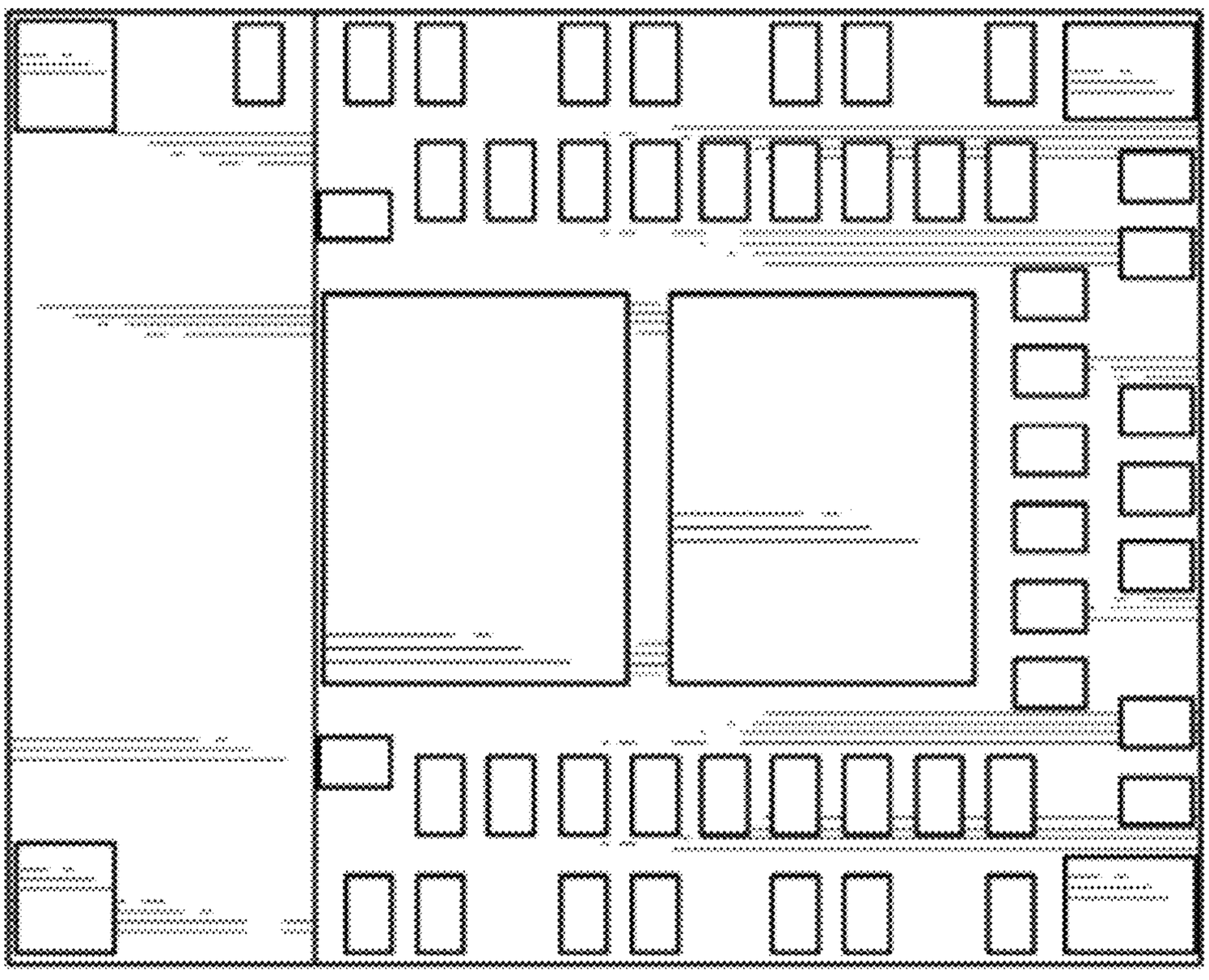

Fig-6